

Transient Voltage Suppressors for ESD Protection

FEATURES:

- Low Leakage
- Response Time is Typically < 1 ns
- IEC61000-4-2 Level 4 ESD Protection
- These are Pb-Free Devices
- We declare that the material of product compliance with RoHS requirements and Halogen Free.

Circuit Diagram & Pin Configuration:







DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
TESDN121AD82	Н	10000/Tape&Reel

MAXIMUM RATINGS

	1		1
Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Air discharge		±15	kV
Contact discharge		±8	kV
ESD Voltage Per Human Body Model		16	kV
Total Power Dissipation on FR-5 Board (Note 1)	PD	150	mW
@ T _A =25			
Junction and Storage Temperature Range	TJ,TSTG	-55 to 150	
Lead Solder Temperature – Maximum (10	TL	260	
Second Duration)			

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0*0.75*0.62 in.

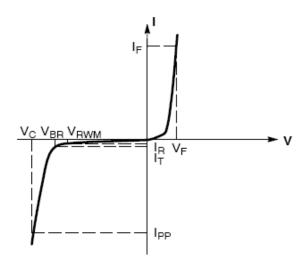


TESDN121AD82

ELECTRICAL CHARACTERISTICS

(T_Δ = 25°C unless otherwise noted)

(TA = 20 O diffess officiwise floted)		
Symbol	Parameter	
I _{PP}	Maximum Reverse Peak Pulse Current	
Vc	Clamping Voltage @ I _{PP}	
V_{RWM}	Working Peak Reverse Voltage	
I _R	Maximum Reverse Leakage Current @ V _{RWM}	
V_{BR}	Breakdown Voltage @ I _T	
I _T	Test Current	
I _F	Forward Current	
V _F	Forward Voltage @ I _F	
P_{pk}	Peak Power Dissipation	
С	Max. Capacitance @V _R = 0 and f = 1 MHz	



Uni-Directional TVS

ELECTRICAL CHARACTERISTICS (T_A=25 unless otherwise noted, VF=0.9V Max. @ IF=10Ma for all types)

	-						, ,	
	V_{RWM}	I_R	V_{BR}	I _T	I _{PP}	V _C	P_{PK}	С
	(V)	(μ A)	(V)	(mA)	(A)	(V)	(W)	(pF)
Device		@	@ I _T			@ Max I _{PP}	(8*20 µs)	
		V_{RWM}	(Note 2)		(Note 3)	(Note 3)		
	Max	Max	Min		Max	Max	Тур	Тур
TESDN121AD82	12	1.0	13.3	1.0	5.9	23.7	140	30

Other voltage available upon request.

- 2. V_{BR} is measured with a pulse test current IT at an ambient temperature of 25
- 3. Surge current waveform per Figure 3.



TYPICAL CHARACTERISTICS

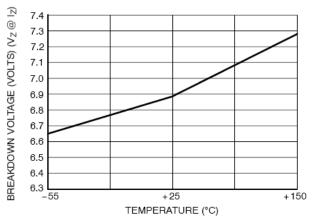


Figure 1. Typical Breakdown Voltage versus Temperature

Fig 2. Typical Leakage Current versus
Temperature

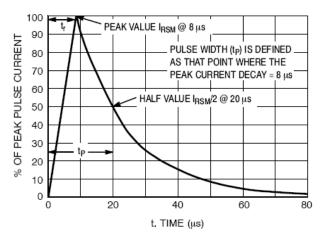
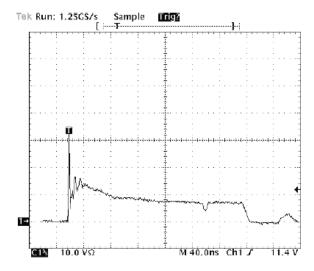
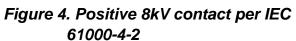


Figure 3. 8*20 s Pulse Waveform





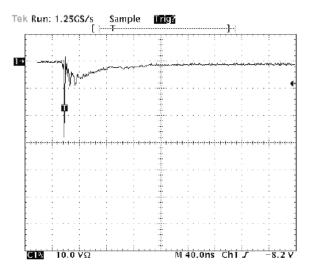
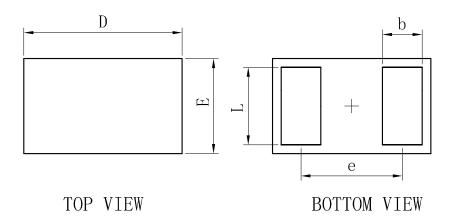


Fig 5. Negative 8kV contact per IEC 61000-4-2

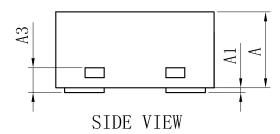


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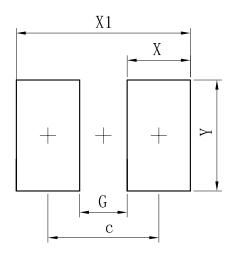
OUTLINE AND DIMENSIONS



S0D882					
3UD00Z					
Dim	Min	Тур	Max		
D	0. 95	1.00	1.05		
Е	0. 55	0.60	0.65		
е	-	0.64	-		
L	0.44	0.49	0. 54		
b	0. 20	0. 25	0.30		
A	0.43	0.48	0. 53		
A1	0	_	0.05		
A3	0. 127REF.				
All Dimensions in mm					



SOLDERING FOOTPRINT



Dimensions	(mm)
С	0.70
G	0.30
X	0.40
X1	1. 10
Y	0.70



TESDN121AD82

NOTICE

The information presented in this document is for reference only. Tinysemi reserves the right to make changes without notice for the specification of the products displayed herein.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Tintsemi elec Co., Ltd., or anyone on its behalf, assumes no responsibility or liability for any damagers resulting from such improper use of sale.

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